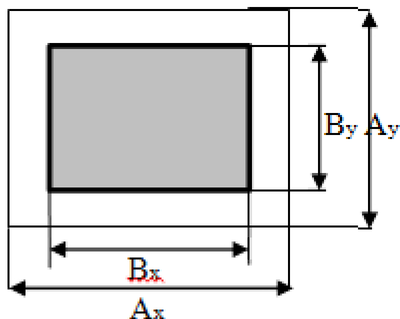
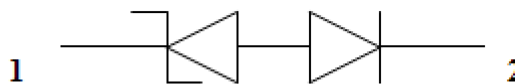
mikron VSP-MIKRON





Mechanical data: A_x=A_y=590um
B_x=B_y=350um
Chip thickness:180+/-15
Scribe Line width - 60um.
Top side – pin 1: Al - metallization for wire bond.
Back side – pin 2: Ti-Ni-Ag for soldering

Schematic and pinning diagram

Limiting values

Parameter	**Symbol**	**Conditions**	**Value**	**Unit**
Peak Pulse Power	P_{PP}	t_p=8/20us	480*	**W**
Peak Pulse Current	I_{PP}	t_p=8/20us	40,0*	**A**
Electrostatic discharge	VESD	IEC 61000-4-2. Level-4. Pin1 to Pin2.	+30,0-Contact. +30,0-Air.	**kV**
Max .junction temperature	T_j	-	+125	**°C**

Characteristics (Ta=25ºC)

SYMBOL	PARAMETER	**CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
V_{rwm}	Reverse Stand-off voltage		-	-	2,5	V
V_{pt}	Punch-Through Voltage.	Ipt=2uA	2,8**	-	-	V
V_{sb}	Snap-Back Voltage.	Isb=50mA	2,5	-	**4,0**	V
Ir	Reverse leakage current	V_R=2,8V; "+"on pin 1	-	-	0,2	uA
Cj	Diode capacitance .	F=1MHz,V_{dc}=0V.	-	85	-	pF
V_{CL}	Clamping voltage	I_R=1A, t_p= 8/20uS I_R=10,0A,t_p=8/20uS I_R= 25,0A, t_D=8/20uS	-	-	4,2* 5,5* 7,5*	V

*- For Device testing.
**- This Parameter guarantied for Device.